Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: <u>ti.com/support</u>

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: **06/09/2022**

Details for "TLV70031DSER"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV70031DSER	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DSE 6	1.5x1.5x0.75	4.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.019565	100	1000000	0.407184	4072
Sub-Total			0.019565	100	1000000	0.407184	4072
Die Attach Adhesive	•	•			·		
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.011773	29.998726	299987	0.245018	2450
Other Inorganic Materials	Silica	7631-86-9	0.001766	4.499936	44999	0.036754	368
Other Organic Materials	Chlorine	7782-50-5	0.000014	0.035673	357	0.000291	3
Thermoplastics	Ероху	85954-11-6	0.025692	65.465664	654657	0.534698	5347
Sub-Total			0.039245	100	1000000	0.816761	8168
Lead Frame		-					
Copper and Its Alloys	Copper	7440-50-8	1.732537	97.050022	970500	36.057314	360573
Copper and Its Alloys	Iron	7439-89-6	0.046415	2.599989	26000	0.965982	9660
Copper and Its Alloys	Phosphorus	7723-14-0	0.002678	0.150011	1500	0.055734	557
Zinc and Its Alloys	Zinc	7440-66-6	0.00357	0.199978	2000	0.074298	743
Sub-Total			1.7852	100	1000000	37.153329	371533
Lead Frame Plating			-				
Nickel and Its Alloys	Nickel	7440-02-0	0.061104	97.300912	973009	1.271688	12717
Precious Metals	Gold	7440-57-5	0.000188	0.299368	2994	0.003913	39
Precious Metals	Palladium	7440-05-3	0.001319	2.100352	21004	0.027451	275
Precious Metals	Silver	7440-22-4	0.000188	0.299368	2994	0.003913	39
Sub-Total			0.062799	100	1000000	1.306964	13070
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	2.231514	84.399998	844000	46.441953	464420
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.138015	5.219983	52200	2.872349	28723
Other Plastics and Rubber	Carbon Black	1333-86-4	0.004759	0.179994	1800	0.099044	990
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.00238	0.090016	900	0.049532	495
Thermoplastics	Ероху	85954-11-6	0.267306	10.110009	101100	5.563135	55631
Sub-Total			2.643974	100	1000000	55.026012	550260
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.25417	100	1000000	5.28975	52897
Sub-Total			0.25417	100	1000000	5.28975	52897
Total			4.804953			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.